

ABSTRACT

A method for fabricating a leadframe structure comprising a chip mount pad and a plurality of lead segments, each having a first end near the mount pad and a second end remote from said mount pad. The structure is formed from a sheet-like starting material. In a first plating system, the leadframe is plated with a layer of nickel. Next, the second segment ends are selectively masked and a layer of palladium is selectively plated on the nickel layer on the exposed chip pad and first segment ends in a thickness suitable for wire bonding attachment. In a second plating system, the chip pad and first segment ends are selectively masked and a pure tin layer is selectively plated on the nickel layer on the exposed second segment ends in a thickness suitable for parts attachment.